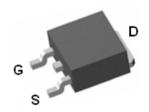




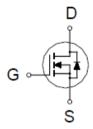
N-Channel Enhancement Mode MOSFET

PRODUCT SUMMARY

V _{(BR)DSS}	R _{DS(ON)}	I _D
25V	$9.5 \text{m}\Omega$ @V _{GS} = 10V	56A



TO-252



ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C Unless Otherwise Noted)

PARAMETERS/TEST C	SYMBOL	LIMITS	UNITS		
Drain-Source Voltage	V_{DS}	25	V		
Gate-Source Voltage	V_{GS}	±20			
Continuous Drain Current	T _C = 25 °C	1	56	А	
Continuous Diain Current	T _C = 100 °C	I _D	35		
Pulsed Drain Current ¹	I _{DM}	160	A		
Avalanche Current	I _{AS}	34			
Avalanche Energy	L = 0.1mH	E _{AS}	60	mJ	
Power Dissipation	T _C = 25 °C	P _D	49	W	
rowei Dissipation	T _C = 100 °C	ı, D	20		
Junction & Storage Temperature Rar	T_J,T_STG	-55 to 150	°C		

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{ heta JC}$		2.55	°C / W
Junction-to-Ambient	$R_{ heta JA}$		63	

¹Pulse width limited by maximum junction temperature.





N-Channel Enhancement Mode MOSFET

ELECTRICAL CHARACTERISTICS (T_J = 25 °C, Unless Otherwise Noted)

DADAMETED	SYMBOL	TEST CONDITIONS	LIMITS				
PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
		STATIC	•				
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	25			V	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.0	1.6	3.0	V	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 25V$			±100	nΑ	
Zero Gate Voltage Drain Current		$V_{DS} = 20V, V_{GS} = 0V$			1	^	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 20V$, $V_{GS} = 0V$, $T_{J} = 125$ °C			10	μΑ	
Drain-Source On-State	D	$V_{GS} = 5V, I_{D} = 20A$		12	19	$m\Omega$	
Resistance ¹	R _{DS(ON)}	$V_{GS} = 10V, I_D = 25A$		7	9.5 S		
Forward Transconductance ¹	g _{fs}	$V_{DS} = 15V, I_{D} = 20A$		60		S	
		DYNAMIC					
Input Capacitance	C _{iss}			1400			
Output Capacitance	C _{oss}	$V_{GS} = 0V, V_{DS} = 15V, f = 1MHz$		300		pF	
Reverse Transfer Capacitance	C_{rss}			190			
Gate Resistance	R_g	$V_{GS} = 0V$, $V_{DS} = 0V$, $f = 1MHz$		1.3		Ω	
Tatal Cata Obana 2	$Q_{g(VGS = 10V)}$			25			
Total Gate Charge ²	$Q_{g(VGS = 5V)}$	$V_{DS} = 0.5V_{(BR)DSS}, I_{D} = 25A$		11		nC	
Gate-Source Charge ²	Q_gs	$V_{DS} = 0.5 V_{(BR)DSS}, I_D = 25 A$		6		nc nc	
Gate-Drain Charge ²	Q_gd			5			
Turn-On Delay Time ²	t _{d(on)}			16			
Rise Time ²	t _r	V_{DS} = 15V, R_L = 15 Ω		25		n°C	
Turn-Off Delay Time ²	t _{d(off)}	$I_D\cong 1A,\ V_{GS}=10V,R_{GEN}=6\Omega$		60		nS	
Fall Time ²	t _f			16			
SOURCE-DR	AIN DIODE F	RATINGS AND CHARACTERISTICS ($T_J = 25$	°C)			
Continuous Current	I _S				37	Α	
Forward Voltage ¹	V_{SD}	$I_F = 25A, V_{GS} = 0V$			1.3	V	
Reverse Recovery Time	t _{rr}	I _F = 25A, dI _F /dt = 100A / μS		35		nS	
Reverse Recovery Charge	Q_{rr}	1= - 20π, αιε/αι - 100π / μο		61		nC	

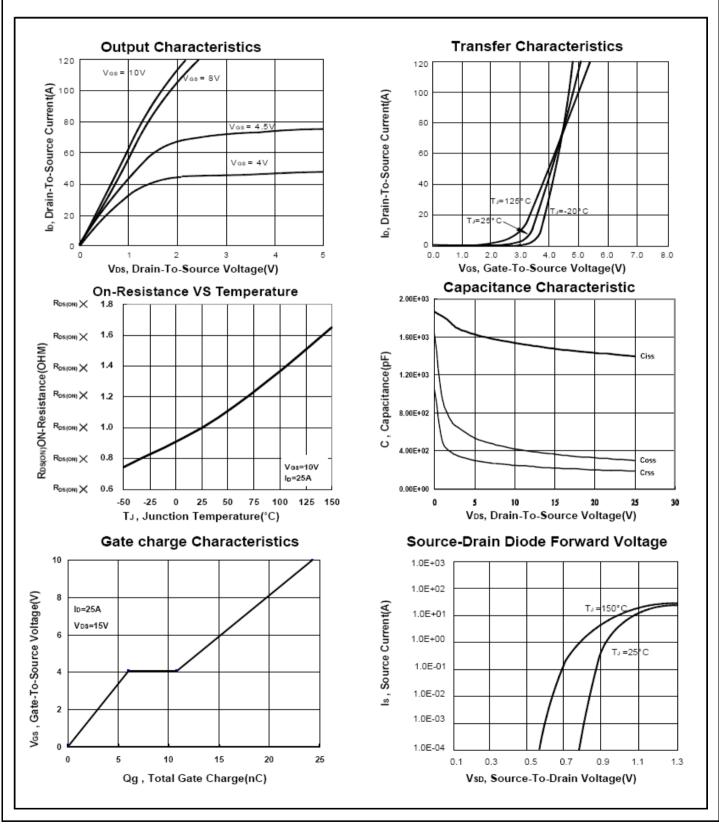
¹Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

²Independent of operating temperature.





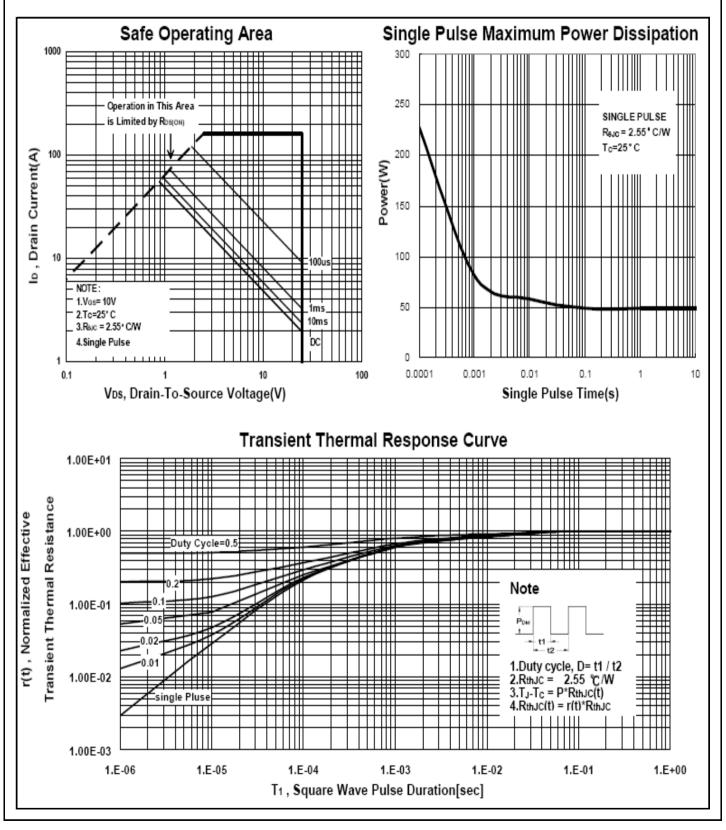
N-Channel Enhancement Mode MOSFET







N-Channel Enhancement Mode MOSFET







N-Channel Enhancement Mode MOSFET

Package Dimension

TO-252 (DPAK) MECHANICAL DATA

Dimension	mm				mm		
	Min.	Тур.	Max.	Dimension	Min.	Typ.	Max.
Α	8.9	10	10.41	J	4.8		5.64
В	2.1	2.2	2.5	K	0.15		1.49
С	0.4	0.5	0.61	L	0.4	0.76	0.91
D	0.82	1.2	1.5	M	4.2	4.58	5
E	0.35	0.5	0.65	S	4.57	5.1	5.52
F	0		0.2	Т	3.81	4.75	5.24
G	5.3	6.1	6.3	U	1.4		1.78
Н	0.5		1.7	V	0.55	1.25	1.7
1	6.3	6.5	6.8				

